PAN75TD32CSA

N-CH 30V Fast Switching MOSFET

V_{DS}=30V, I_D=85A, $RDS_{(ON)}$=2.4mΩ

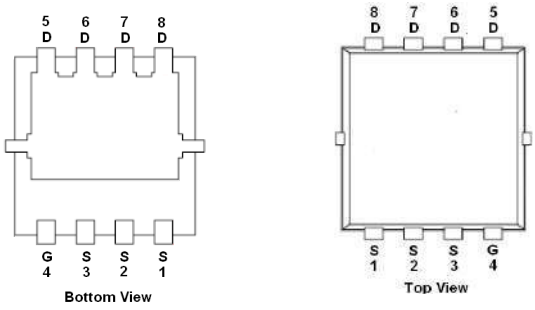
➢ General Description

This PAN75TD32CSA N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

➢ Feature

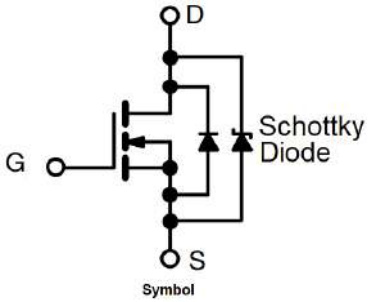
- ●Green Device Available
- ●Super Low Gate Charge
- ●MOSFET with integrated Schottky Diode
- ●100% EAS Guaranteed
- ●Excellent CdV/dt effect decline
- ●Advanced high cell density Trench technology
- ●DFN3.3x3.3-8L package design

➢ DFN3.3x3.3-8L



➢ Application

- ●DC/DC Converters
- ●POL



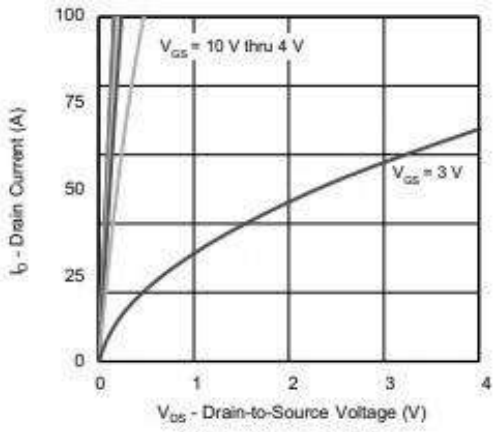
➢ Absolute Maximum Ratings

Parameter			Symbol	Typical		Unit
Drain-Source Voltage			V_{DSS}	30		V
Gate –Source Voltage			V_{GSS}	±20		V
Continuous Drain Current(T_J=150℃)	T_C=25℃	T_C=70℃	I_{DSM}	85	65	A
	T_A=25℃	T_A=70℃		35	28	
Pulsed Drain Current (t=100us)			I_{DM}	150		
Continuous Source Current(Diode Conduction)	T_C=25℃		I_S	25		
	T_A=25℃			3.5		
Single Pulse Avalanche Current	L=0.1mH		I_{AS}	20		
			E_{AS}	20		mJ
Power Dissipation	T_C=25℃	T_C=75℃	P_D	30	20	W
	T_A=25℃	T_A=75℃		4.5	2.8	
Operating Junction Temperature			T_J	150		℃
Storage Temperature Range			T_{STG}	-55/150		℃
Thermal Resistance-Junction to Ambient	t ≤ 10 s		$R_{\theta JA}$	22		℃/W
Maximum Junction-to-Case (Drain)	Steady-State		$R_{\theta JA}$	1.7		

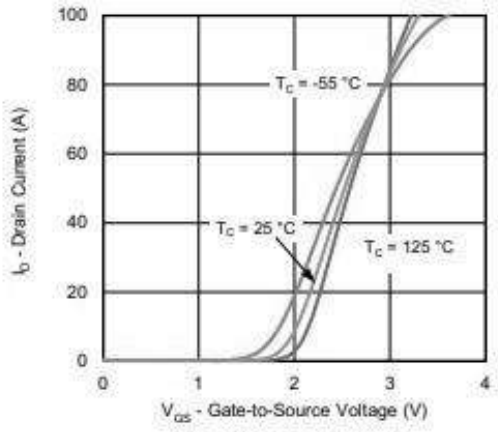
➢ Electrical Characteristics (T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS}=0V,I_D=250uA	30			V
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250uA	1.0	1.5	2.0	
Gate Leakage Current	I_{GSS}	V_{DS}=0V,V_{GS}=±20V			±100	nA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=24V,V_{GS}=0V			500	uA
		V_{DS}=24V,V_{GS}=0V T_J=125℃		200		
On-State Drain Current	$I_{D(on)}$	V_{DS}≧5V,V_{GS}=10V	30			A
Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS}=10V,I_D=20A		2.0	2.4	mΩ
		V_{GS}=4.5V,I_D=15A		2.7	3.5	
Forward Transconductance	g_{FS}	V_{DS}=10V,I_D=19A		230		S
Diode Forward Voltage	V_{SD}	I_S=2A,V_{GS}=0V		0.48	0.7	V
Dynamic						
Total Gate Charge	Q_g	V_{DS}=15V,V_{GS}=4.5V I_D≡19A		15	24	nC
Gate-Source Charge	Q_{gs}			7.1		
Gate-Drain Charge	Q_{gd}			3.4		
Gate Resistance	R_g	f=1MHz	0.4	1.8	3.6	Ω
Input Capacitance	C_{iss}	V_{DS}=15V,V_{GS}=0V f=1MHz		1880		pF
Output Capacitance	C_{oss}			1050		
Reverse Transfer Capacitance	C_{rss}			48		
Turn-On Time	$t_{d(on)}$	V_{DD}=15V,R_L=1.5Ω I_D≡10A,V_{GEN}=10V R_G=1.0Ω		15	30	ns
	t_r			10	20	
Turn-Off Time	$t_{d(off)}$			30	60	
	t_f			10	20	

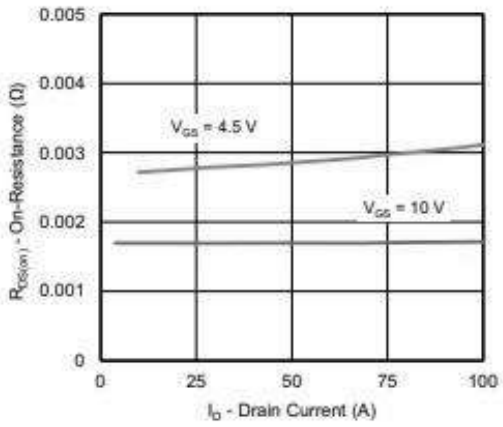
➢ Typical Characteristics



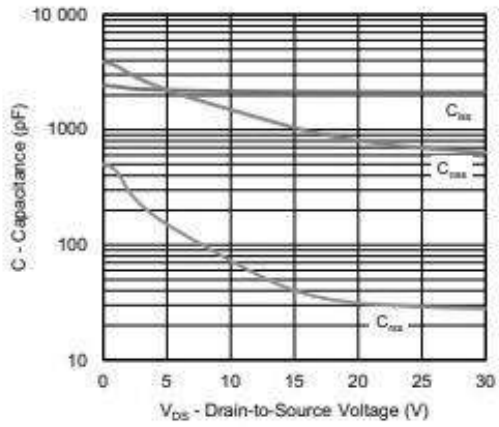
Output Characteristics



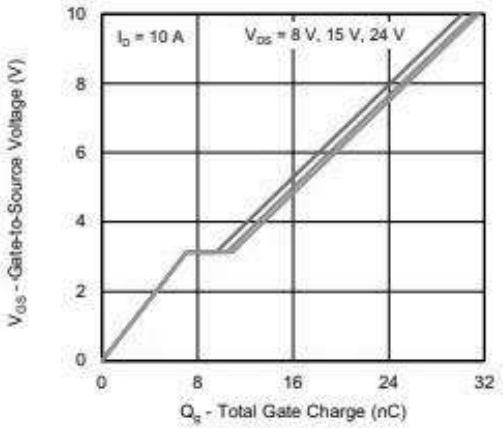
Transfer Characteristics



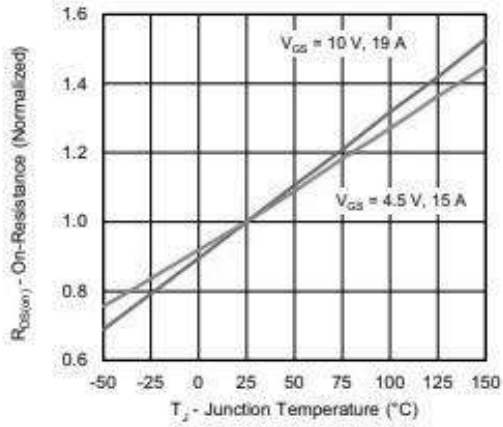
On-Resistance vs. Drain Current



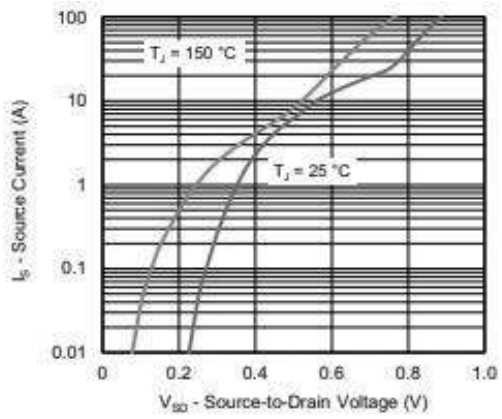
Capacitance



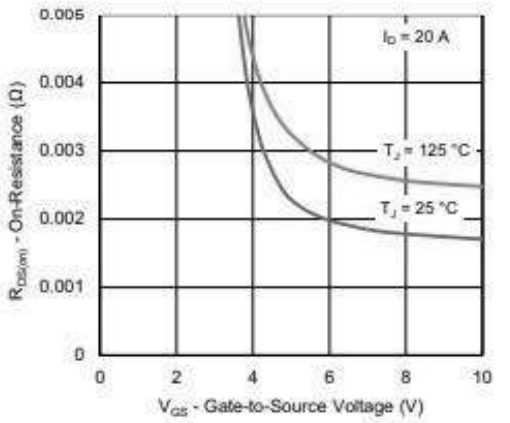
Gate Charge



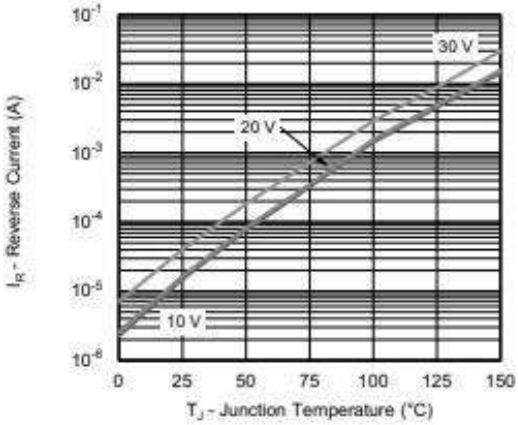
On-Resistance vs. Junction Temperature



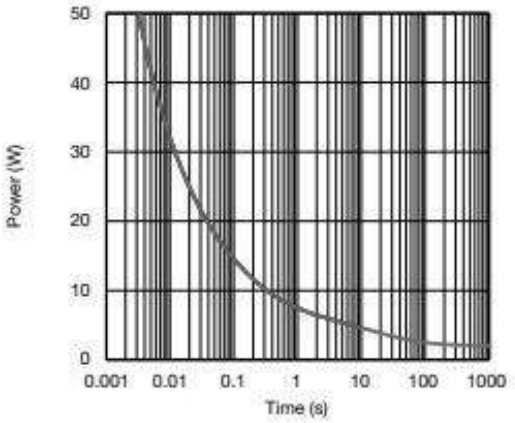
Source-Drain Diode Forward Voltage



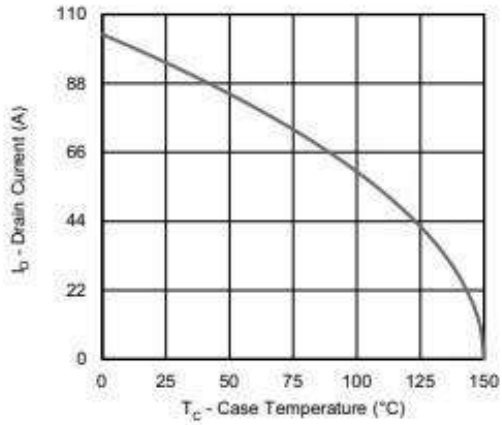
On-Resistance vs. Gate-to-Source Voltage



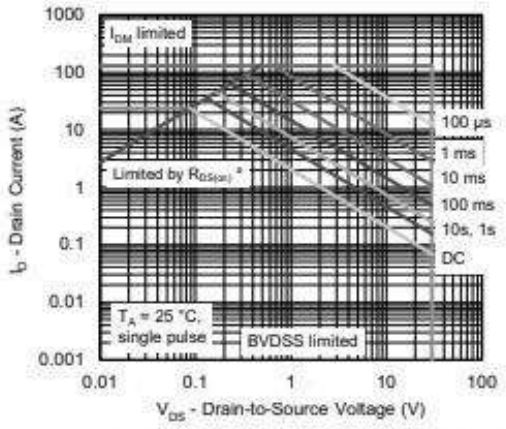
Reverse Current (Schottky)



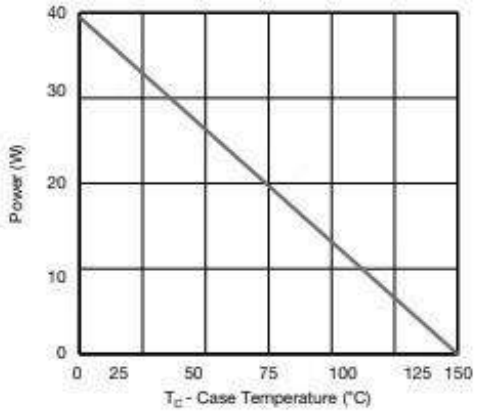
Single Pulse Power, Junction-to-Ambient



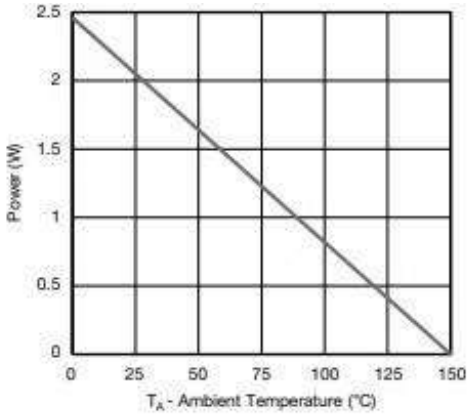
Current Derating [a]



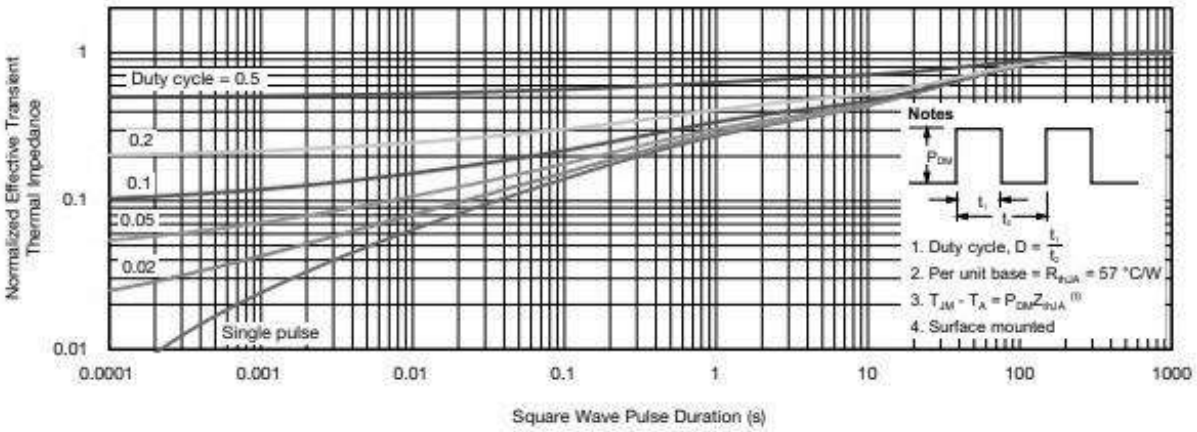
Safe Operating Area, Junction-to-Ambient



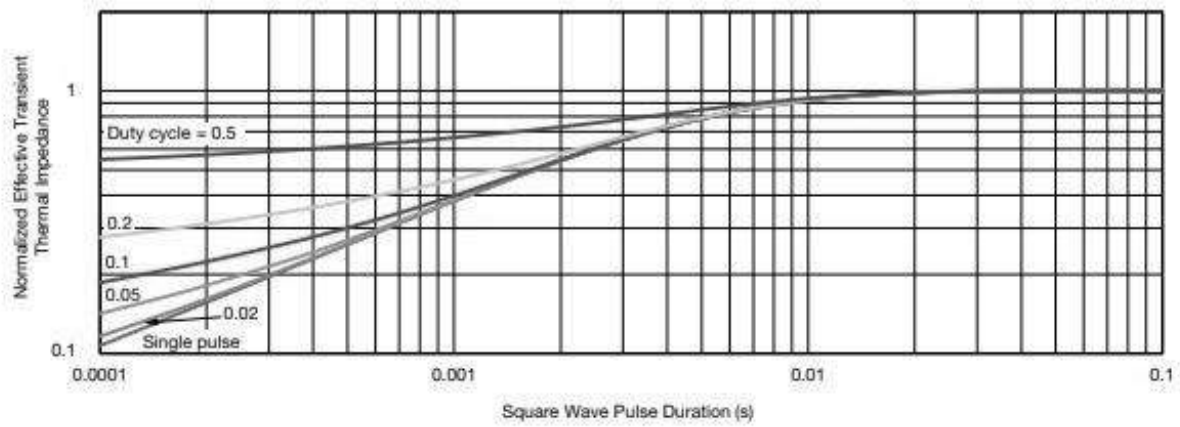
Power, Junction-to-Case



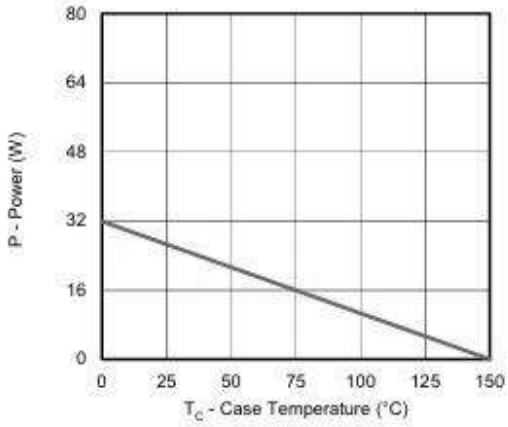
Power, Junction-to-Ambient



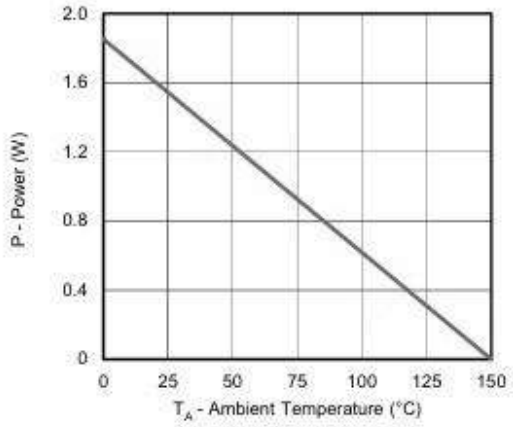
Normalized Thermal Transient Impedance, Junction-to-Ambient



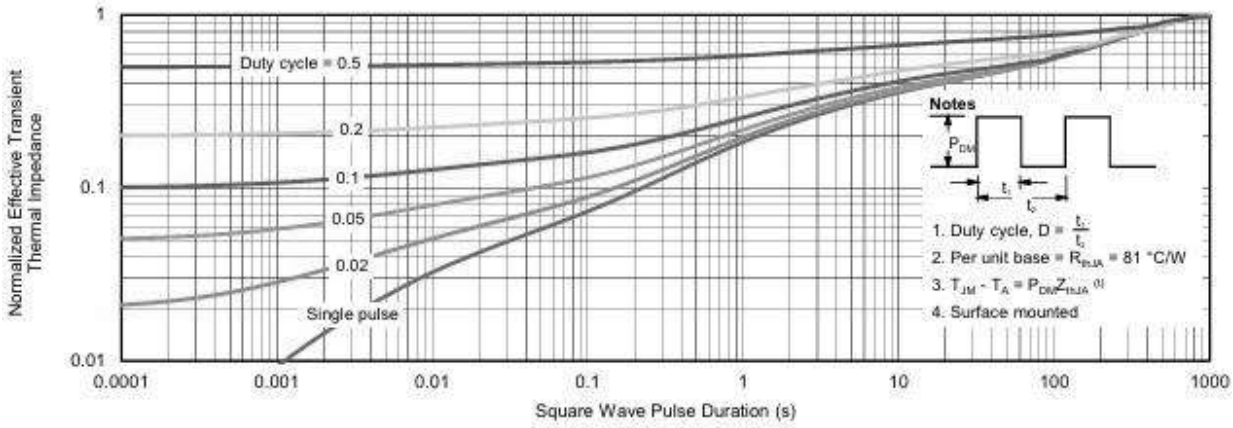
Normalized Thermal Transient Impedance, Junction-to-Case



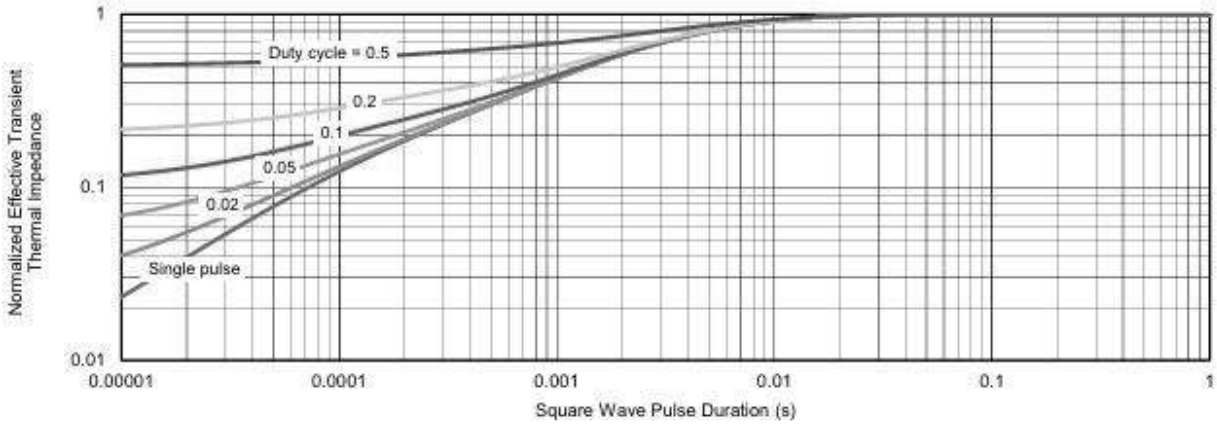
Power, Junction-to-Case



Power, Junction-to-Ambient

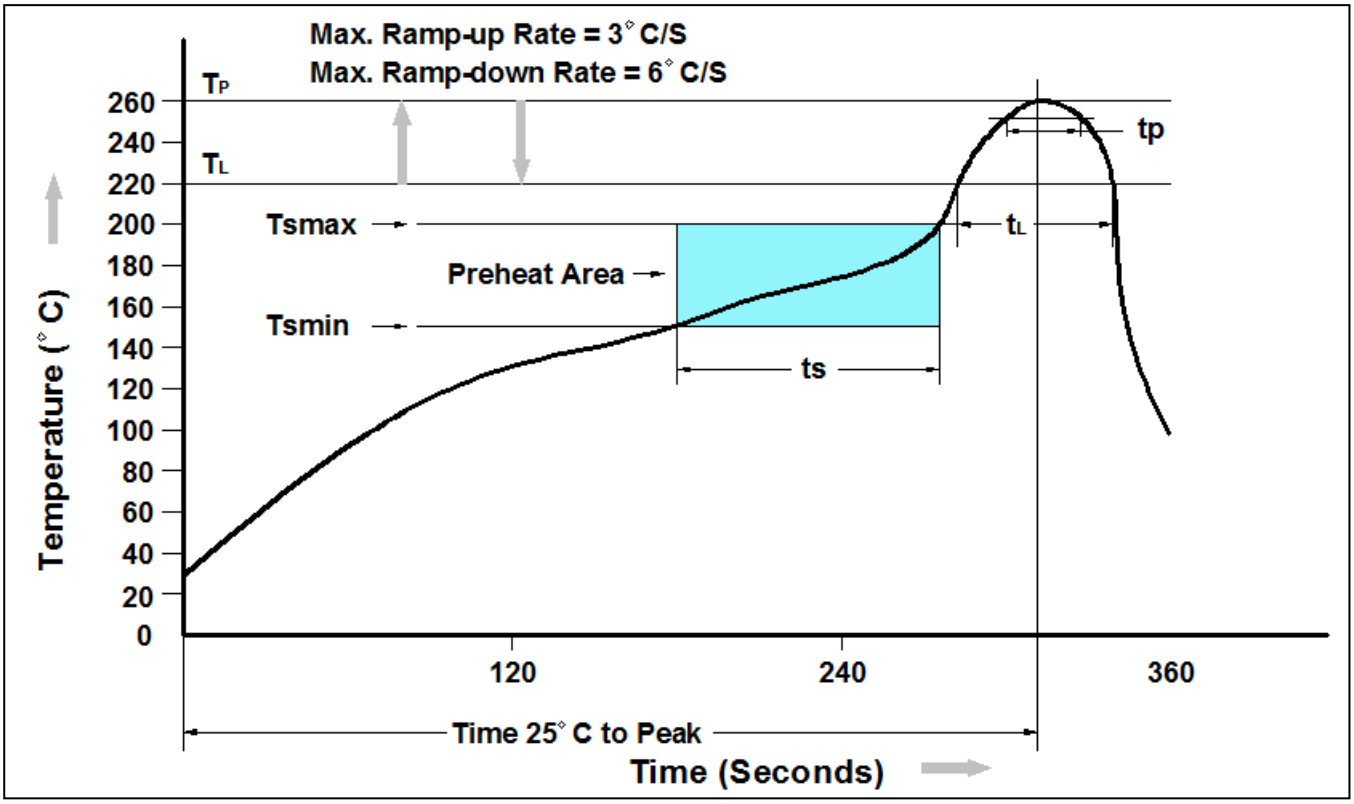


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

➢ Recommand IR Reflow Soldering Thermal Profile

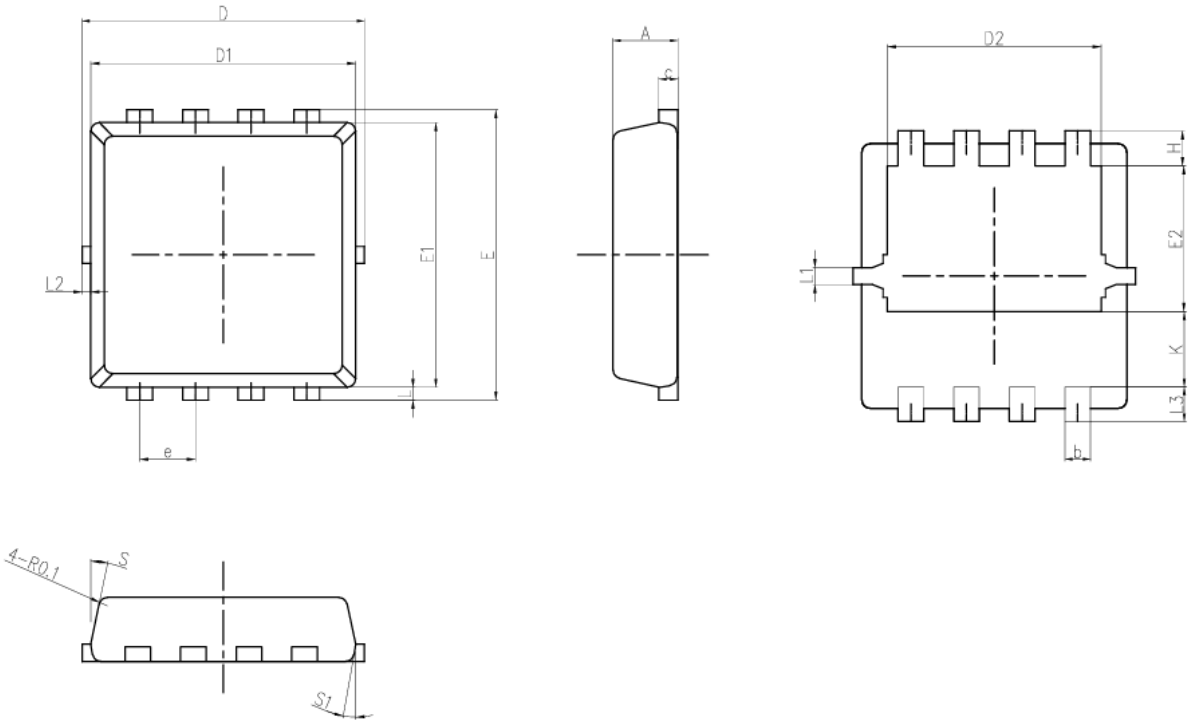


Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Average Ramp-up Rate (tL to tP)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60 – 150 seconds
Peak Temperature	260°C +0°C / -5°C
Time (tP) within 5°C of actual Peak Temperature	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

➢ Ordering Information

Part Number	Description	Quantity
PAN75TD32CSA	DFN3.3x3.3-8L Reel	5000 pcs

➢ Package Information (DFN3.3X3.3-8L)



COMMON DIMENSIONS (UNIT of MEASURE=MILLIMETER)											
SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX	SYMBOL	MIN	NOM	MAX
A	0.66	0.76	0.86	e	0.55	0.65	0.75	L	0.06	0.15	0.20
b	0.25	0.30	0.35	E	3.15	3.30	3.45	L1	0.10	0.20	0.30
c	0.19	0.20	0.22	E1	3.00	3.10	3.20	L2	0	0.10	0.15
D	3.05	3.30	3.45	E2	1.60	1.70	1.80	L3	0.30	0.40	0.50
D1	3.00	3.10	3.20	H	0.31	0.41	0.51	S	10°	12°	14°
D2	2.40	2.50	2.60	K	0.79	0.89	0.99	S1	8°	10°	12°

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